

## HP80N70

### 70V N -Channel MOSFET

#### FEATURES

- ❑ Originative New Design
- ❑ Superior Avalanche Rugged Technology
- ❑ Robust Gate Oxide Technology
- ❑ Very Low Intrinsic Capacitances
- ❑ Excellent Switching Characteristics
- ❑ Unrivalled Gate Charge : 22 nC (Typ.)
- ❑ Extended Safe Operating Area
- ❑ Lower  $R_{DS(ON)}$  : 7m $\Omega$  (Typ.) @ $V_{GS}=10V$
- ❑ 100% Avalanche Tested

$$BV_{DSS} = 70V$$

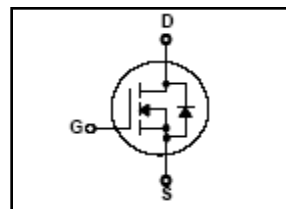
$$R_{DS(on) \text{ typ}} = 7 \text{ m}\Omega$$

$$I_D = 80 \text{ A}$$

TO-220



1.Gate 2. Drain 3. Source



#### Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Value	Units
$V_{DSS}$	Drain-Source Voltage	70	V
$I_D$	Drain Current – Continuous ( $T_C = 25^\circ\text{C}$ )	80	A
	Drain Current – Continuous ( $T_C = 100^\circ\text{C}$ )	60A	A
$I_{DM}$	Drain Current – Pulsed (Note 1)	350	A
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	230	mJ
$I_{AR}$	Avalanche Current (Note 1)	28	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	20	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.8	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	180	W
	– Derate above $25^\circ\text{C}$	1.3	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

#### Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	0.75	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Case-to-Sink	0.5	--	
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	

**70V<sub>DS</sub>/±25V<sub>GS</sub>/80A(I<sub>D</sub>) N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics (T<sub>A</sub>=25°C Unless Otherwise Specified)**

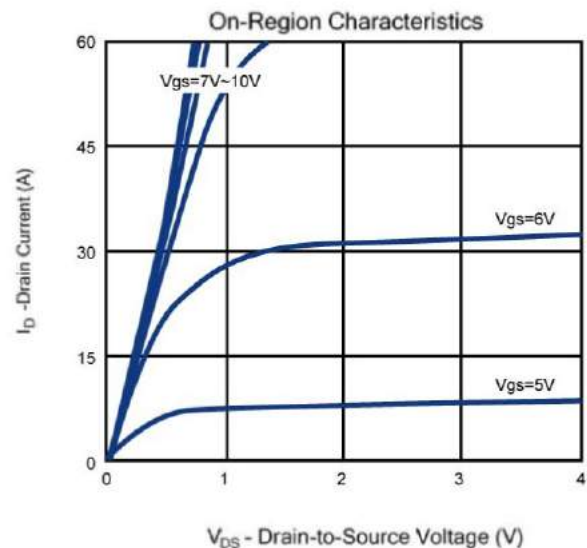
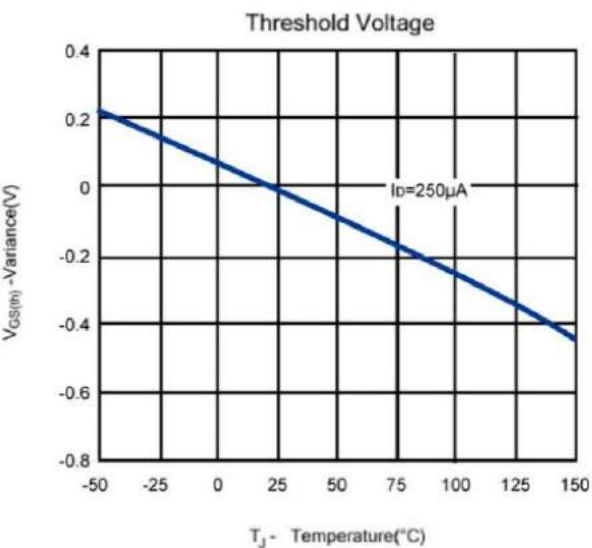
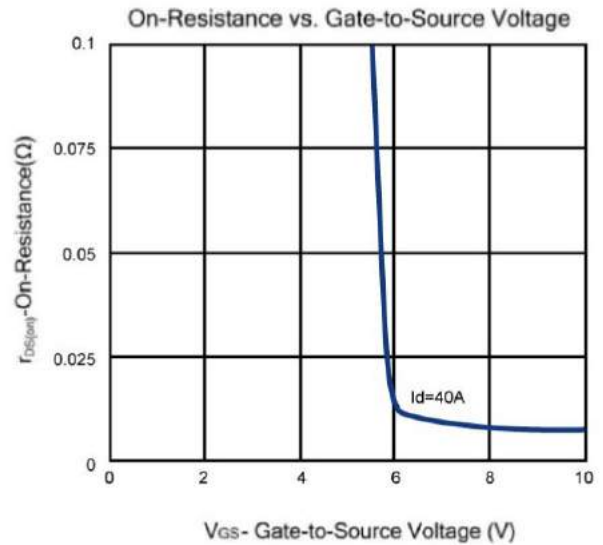
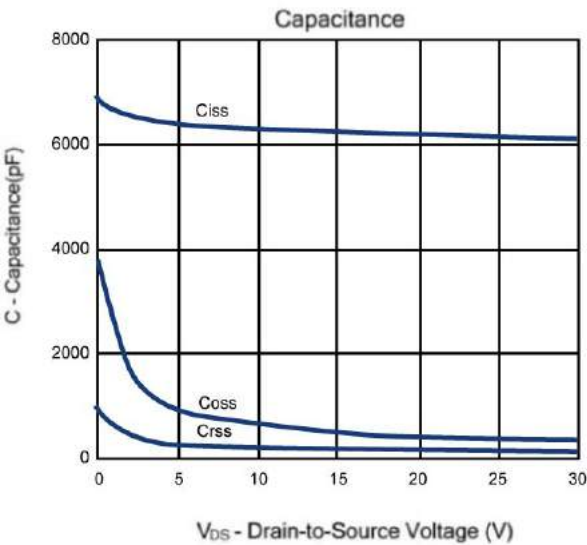
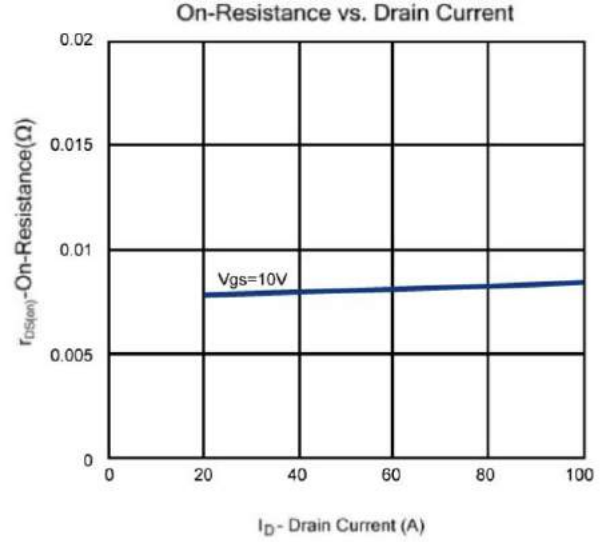
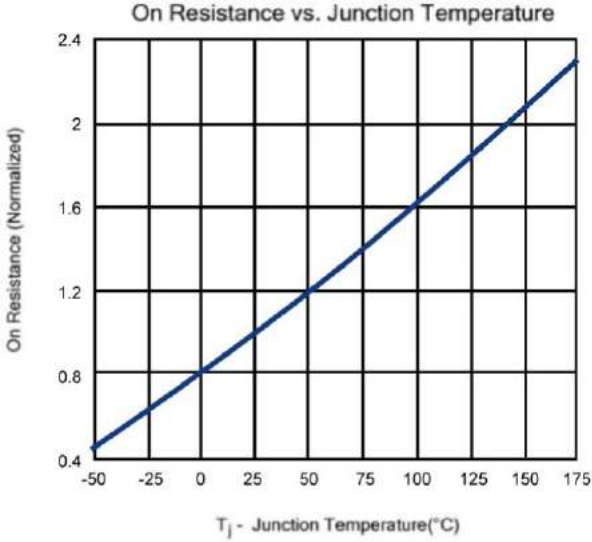
<b>STATIC</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250 μA	70			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	2.0		4.0	V
I <sub>GSS</sub>	Gate-Body Leakage	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =70V, V <sub>GS</sub> =0V			1	μA
R <sub>DS(ON)</sub>	Drain-Source On-Resistance*	V <sub>GS</sub> =10V, I <sub>D</sub> =40A		7	8.5	mΩ
V <sub>SD</sub>	Diode Forward Voltage *	I <sub>S</sub> =40A, V <sub>GS</sub> =0V		0.9	1.3	V
<b>DYNAMIC</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DD</sub> =70V, V <sub>GS</sub> =10V, I <sub>D</sub> =80A		134		nC
Q <sub>g</sub>	Total Gate Charge	V <sub>DD</sub> =70V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =80A		27		
Q <sub>gs</sub>	Gate-Source Charge			36		
Q <sub>gd</sub>	Gate-Drain Charge			50		
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz		0.8		Ω
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHz		6200		pF
C <sub>oss</sub>	Output Capacitance			437		
C <sub>rss</sub>	Reverse Transfer Capacitance			144		
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =10V, R <sub>L</sub> =15Ω V <sub>DD</sub> =30V, R <sub>G</sub> =10Ω		60		ns
t <sub>r</sub>	Turn-On Rise Time			43		
t <sub>d(off)</sub>	Turn-Off Delay Time			159		
t <sub>f</sub>	Turn-Off Fall Time			47		

Notes: a. pulse test: pulse width ≤ 300us, duty cycle ≤ 2%, Guaranteed by design, not subject to production testing.

b. Matsuki reserves the right to improve product design, functions and reliability without notice.

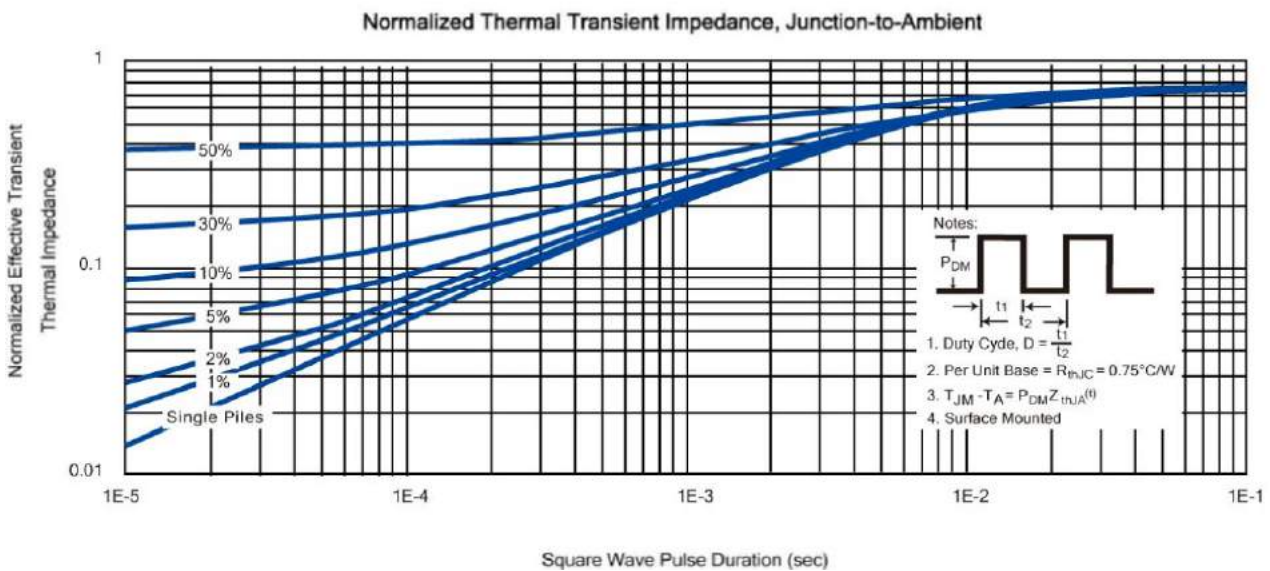
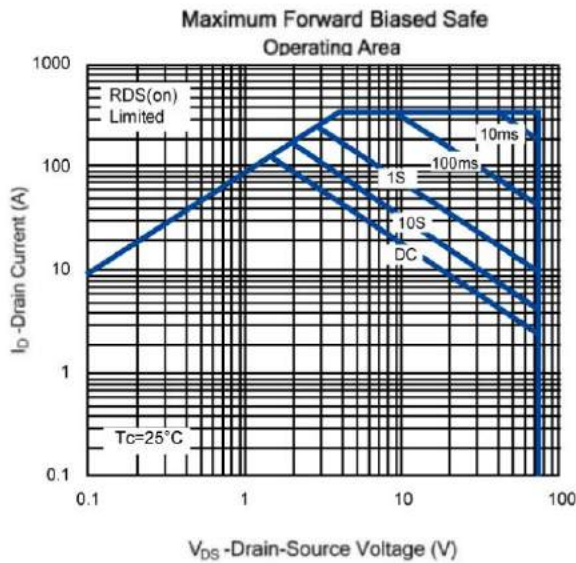
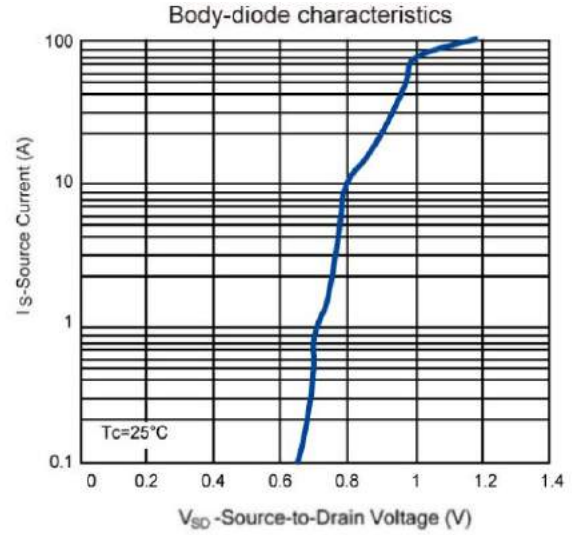
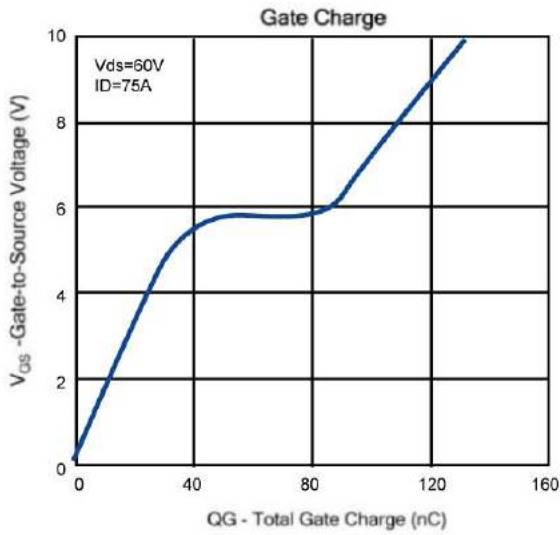
## 80V<sub>DS</sub>/±25V<sub>GS</sub>/70A(I<sub>D</sub>) N-Channel Enhancement Mode MOSFET

### Typical Characteristics (T<sub>J</sub> = 25°C Noted)



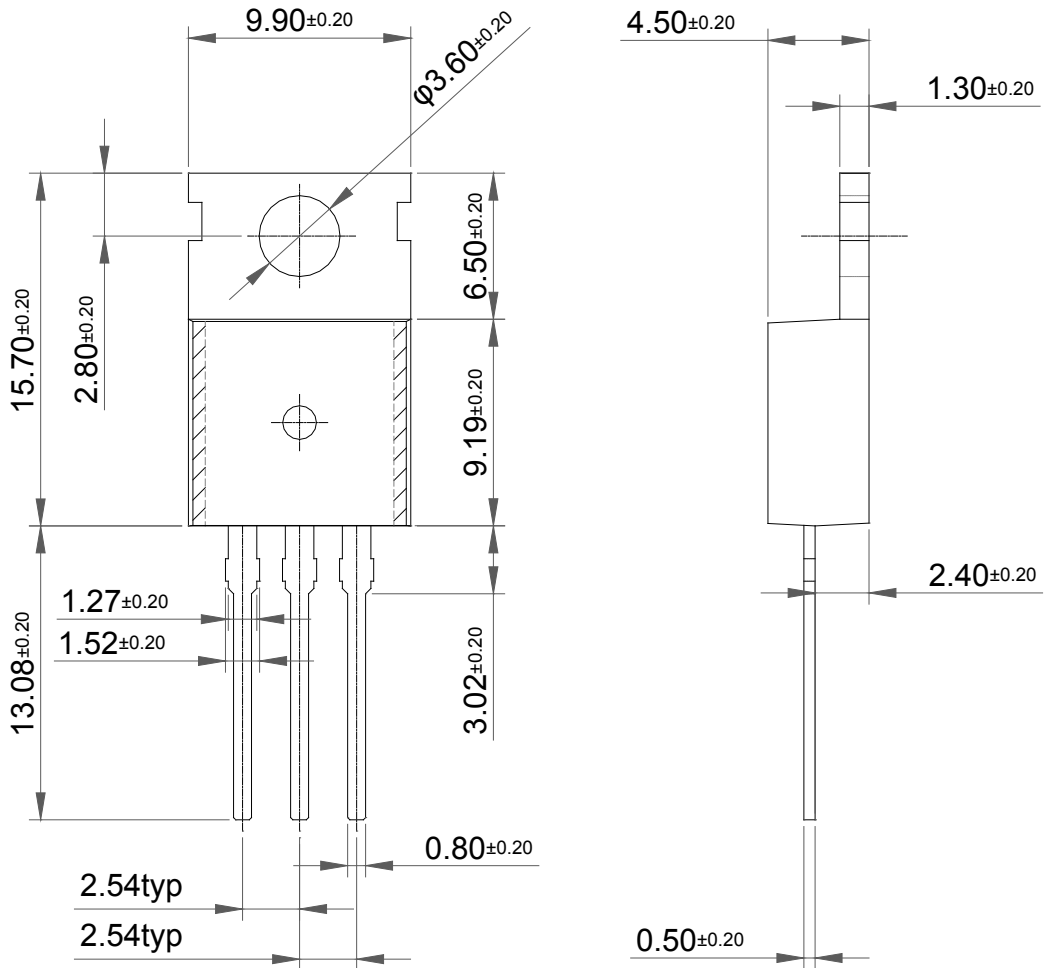
**70V<sub>DS</sub>/±25V<sub>GS</sub>/80A(I<sub>D</sub>) N-Channel Enhancement Mode MOSFET**

**Typical Characteristics (T<sub>J</sub> = 25°C Noted)**



Package Dimension

TO-220 (A)



# TO-220 (B)

